

ABSTRACT OF THE DISCLOSURE

A method of manufacturing a mini-card with a semiconductor memory device includes the steps of (a) providing an array of substrates including a plurality of individual substrates; (b) mounting a semiconductor memory device on each of the individual substrates forming the substrate array; (c) covering the individual substrates with respective cases; and (d) dividing the substrate array to provide encased individual substrates each completing a mini-card having the semiconductor memory device embedded therein.

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